Schottky Barrier Diode

NSR10F20NXT5G

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current and are offered in a Chip Scale Package (CSP) to reduce board space. The low thermal resistance enables designers to meet the challenging task of achieving higher efficiency and meeting reduced space requirements.

Features

- Low Forward Voltage Drop – 430 mV @ 1.0 A
- Low Reverse Current – 20 μA @ 10 V VR
- 1.0 A of Continuous Forward Current
- ESD Rating – Human Body Model: Class 3B
  – Machine Model: Class C
- High Switching Speed
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc−dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

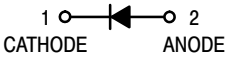
- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

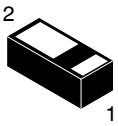
MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	20	V
Forward Current (DC)	I_F	1.0	A
Forward Surge Current (60 Hz @ 1 cycle)	I_{FSM}	18	A
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)	I_{FRM}	4.0	A
ESD Rating: Human Body Model Machine Model	ESD	> 8 > 400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

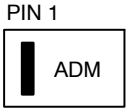
20 V SCHOTTKY BARRIER DIODE





DSN2 (0502) CASE 152AD

MARKING DIAGRAM



AD = Specific Device Code
M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR10F20NXT5G	DSN2 (Pb−Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Typ	Max	Unit
Thermal Resistance Junction−to−Ambient (Note 1) Total Power Dissipation @ T_A = 25°C	 $R_{\theta JA}$ P_D			 228 548	 °C/W mW
Thermal Resistance Junction−to−Ambient (Note 2) Total Power Dissipation @ T_A = 25°C	 $R_{\theta JA}$ P_D			 85 1.47	 °C/W W
Storage Temperature Range	T_{stg}			−40 to +125	°C
Junction Temperature	T_J			+150	°C

1. Mounted onto a 4 in square FR−4 board 50 mm sq. 1 oz. Cu 0.06” thick single sided. Operating to steady state.
2. Mounted onto a 4 in square FR−4 board 1 in sq. 1 oz. Cu 0.06” thick single sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Leakage (V_R = 10 V) (V_R = 20 V)	I_R			 20 100	μA
Forward Voltage (I_F = 0.5 A) (I_F = 1.0 A)	V_F		 0.380 0.430	 0.400 0.450	V

TYPICAL CHARACTERISTICS

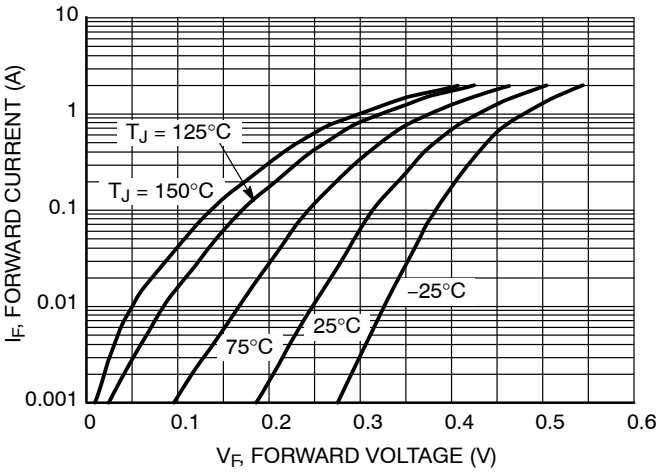


Figure 1. Forward Voltage

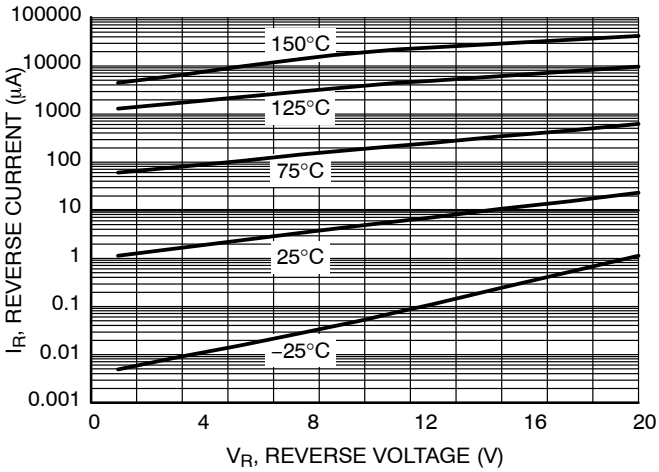


Figure 2. Typical Reverse Current

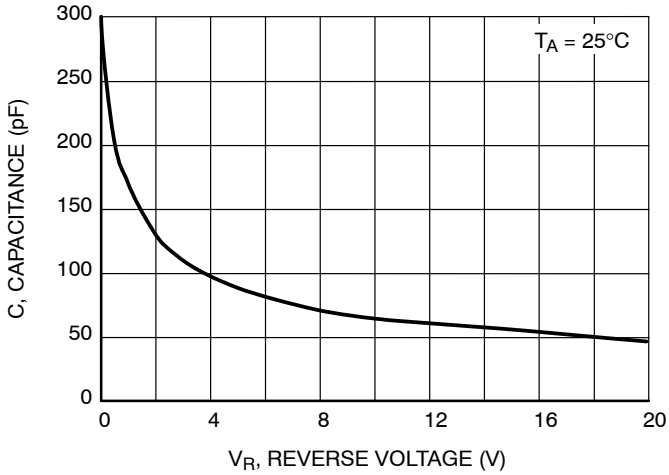
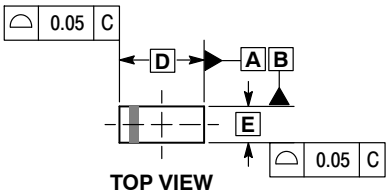


Figure 3. Typical Capacitance

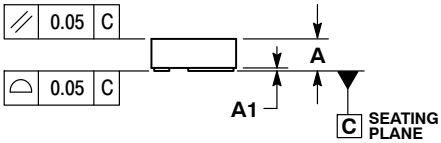
SCALE 8:1

DSN2, 1.4x0.6, 0.75P
CASE 152AD
ISSUE C

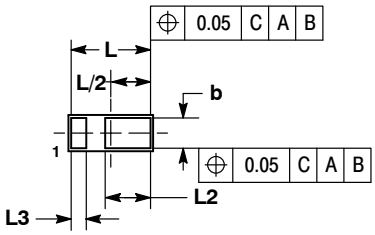
DATE 24 APR 2017



TOP VIEW



SIDE VIEW

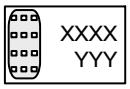


BOTTOM VIEW

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.25	0.31
A1	---	0.05
b	0.45	0.55
D	1.40 BSC	
E	0.60 BSC	
L	1.20	1.30
L2	0.70	0.80
L3	0.20	0.30

GENERIC MARKING DIAGRAM1*



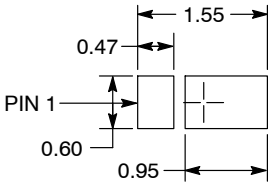
XXXX = Specific Device Code
YYY = Year Code

GENERIC MARKING DIAGRAM2*

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G”, may or not be present. Some products may not follow the Generic Marking.

MOUNTING FOOTPRINT*

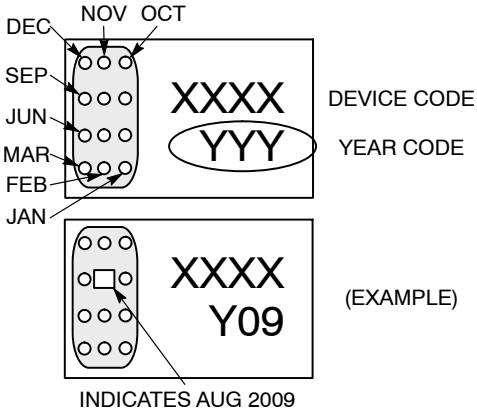


DIMENSIONS: MILLIMETERS

See Application Note AND8464/D for more mounting details

*For additional information on our Pb−Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

CATHODE BAND MONTH CODING



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DESCRIPTION:	DSN2, 1.4X0.6, 0.75P	PAGE 1 OF 1

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